

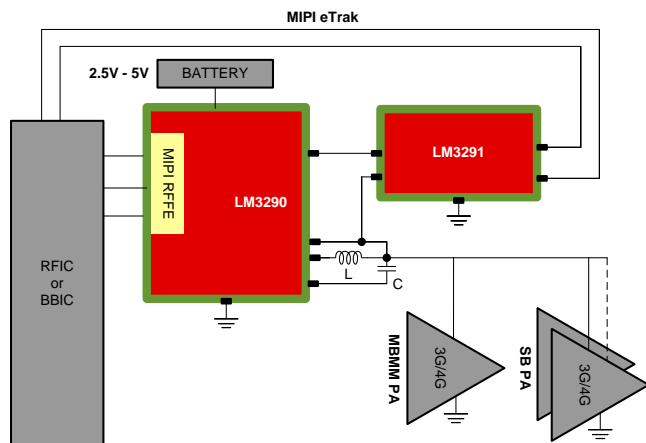
LM3291 Product Brief

FEATURES

- **Highly Programmable High-Current Linear Amplifier**
- **> 75 MHz Typical Small Signal Bandwidth**
- **Extremely Low Output Impedance**
- **High Linearity**
- **Differential Analog Input Compatible with eTrak 1.0 Standard**
- **Low Output Noise**
- **When paired with the LM3290 provides a complete Envelope Modulator solution for 3G/4G Envelope Tracking Power Amplifiers.**
- **Automatically controlled through LM3290 in an envelope modulation solution using MIPI® RFFE 1.1-compatible interface.**

APPLICATIONS

- **3G/LTE Handsets**
- **3G/LTE Tablets**
- **3G/LTE Data Cards and Wireless Modems**



DESCRIPTION

The LM3291 is a high-speed linear amplifier that, with its companion IC LM3290, constitutes an RF Envelope Modulator (EM) for supplying 3G/4G Power Amplifiers (PA) in envelope tracking systems. The amplifier provides extremely low output impedance and low output noise over a wide bandwidth.

In conjunction with an Envelope Tracking (ET) capable RFIC and PA, the LM3291 and LM3290 greatly improve PA efficiency for 3G and LTE operation.

In ET mode, the LM3291 and LM3290 provide envelope tracking supply voltage for the PA maximizing total EM + PA efficiency. The envelope modulator follows the differential envelope reference input signal delivered by the RFIC to the LM3291. The output is a single-ended dynamic power supply voltage to the PA.

The LM3291 supports 3G and LTE operation up to 20 MHz signal bandwidth.

The LM3291's programmable parameters are controlled by LM3290 via a direct serial interface between the two devices. No additional controls are needed in the system. This interface provides flexible control and adjustment options to optimize LM3291 efficiency and noise performance for various frequency bands and power levels.

At high TX output power, the EM can be operated in ET mode where LM3290 and LM3291 together modulate the supply of the PA with the envelope signal to improve overall system efficiency. At low TX output power, the EM can be transitioned to Average Power Tracking (APT) mode where LM3291 is placed into shutdown mode to improve system efficiency.

The LM3291 is available in a 12-pin lead-free DSBGA package.

For the full datasheet, samples, or the EVM hardware and software please contact a TI representative at ET@list.ti.com.



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PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead finish/ Ball material (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
LM3291TME/NOPB	NRND	DSBGA	YFQ	12	250	RoHS & Green	SNAGCU	Level-1-260C-UNLIM	-30 to 85	AE	

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSELETE: TI has discontinued the production of the device.

(2) **RoHS:** TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

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(3) MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "-" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

(6) Lead finish/Ball material - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

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